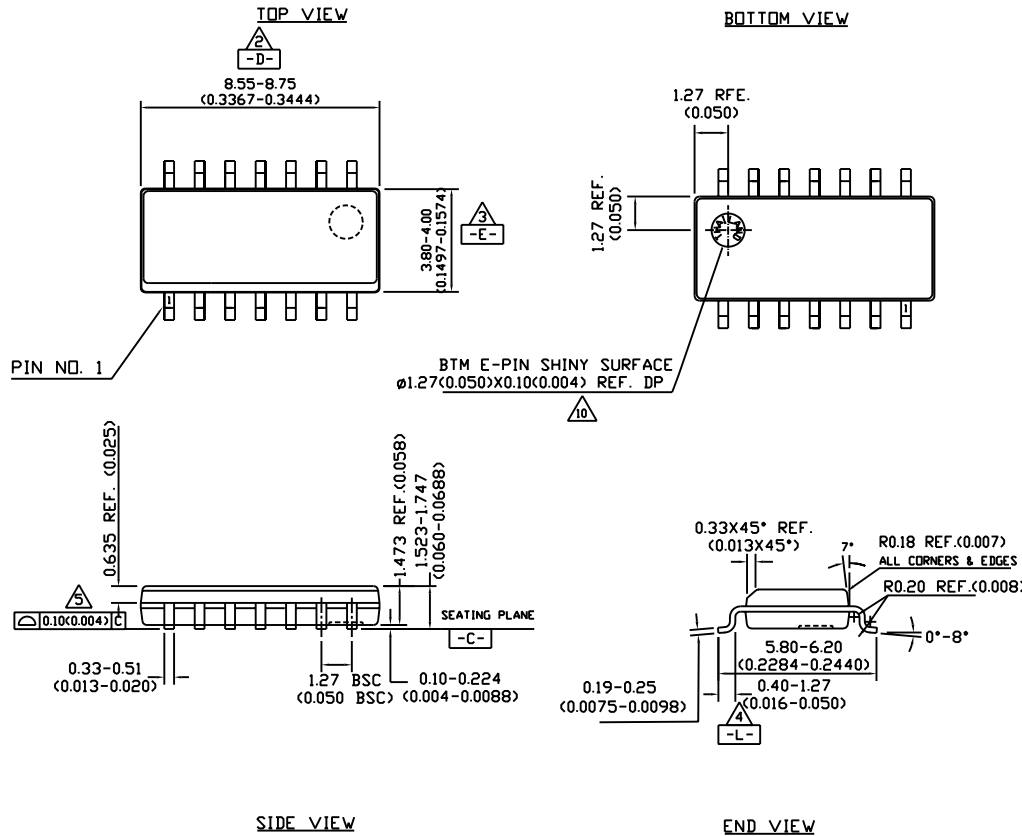



REV	DESCRIPTION	DATE
A	ORIGINAL ISSUE	JUL 6'00



- NOTES:  
 1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1982.  
 2. DIMENSION "D" DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSION OR GATE BURRS SHALL NOT EXCEED 0.15MM(0.006") PER SIDE.  
 3. DIMENSION "E" DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSION, INTER-LEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.25MM(0.010") PER SIDE.  
 4. "L" IS A LENGTH OF TERMINAL FOR SOLDERING TO SUBSTATE.  
 5. FORMED LEAD SHALL BE PLANED WITH RESPECT TO ONE ANOTHER WITHIN 0.10MM(0.004") AT SEATING PLANE "C".  
 6. BODY FINISH : 18-24 CHARMILLES.  
 7. CONTROLLING DIMENSION : MILLIMETER CONVERTED INCH DIMENSION ARE NOT NECESSARILY EXACT.  
 8. LEAD FINISH IS ELECTROPLATING WITH A THICKNESS OF 300 - 800 MICROINCH.  
 9. CHARACTER HEIGHT ON EJECTOR PIN IS 0.25MM(0.0098").  
 10. RAISED CHARACTER NOT TO PROTRUDE BEYOND SURFACE OR PACKAGE BODY.

	DRAWN BY: ANUPHAB U.	TITLE: <b>14 LD SOIC (JEDEC) PACKAGE OUTLINE DWG.          150 MIL BODY WIDTH FAMILY (MGP MOLD)</b>			
	CHECKED BY: NATAPORN C.				
	APPROVED BY: THANAPONG I.	DATE : JUL 6'00	REF. NO. : JEDEC-MS-012	SCALE : NOT TO SCALE	
	APPROVED BY: VIRAT T.	DWG. NO. <b>J014PO-01</b>	REV. A	SHEET 1 OF 1	